

# Multilayer Ceramic Chip Capacitors

#### C3216X7R1H474K160AA



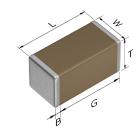






### **TDK item description** C3216X7R1H474KT\*\*\*\*

| Applications | Commercial Grade  Please refer to Part No. CGA5L2X7R1H474K160AA for Automotive use. |  |
|--------------|---|--|
| Feature      | General General (Up to 75V)   |  |
| Series       | C3216 [EIA 1206]  |  |
| Status       | Production (Not Recommended for New Design)   |  |
| Brand        | TDK   |  |



|                                  | Size                               |
|----------------------------------|------------------------------------|
| Length(L)                        | 3.20mm ±0.20mm                     |
| Width(W)                         | 1.60mm ±0.20mm                     |
| Thickness(T)                     | 1.60mm ±0.20mm                     |
| Terminal Width(B)                | 0.20mm Min.                        |
| Terminal Spacing(G)              | 1.00mm Min.                        |
| Recommended Land Pattern (PA)    | 2.10mm to 2.50mm(Flow Soldering)   |
| neconinienceu Lanu Fatterii (FA) | 2.00mm to 2.40mm(Reflow Soldering) |
| Recommended Land Pattern (PB)    | 1.10mm to 1.30mm(Flow Soldering)   |
|                                  | 1.00mm to 1.20mm(Reflow Soldering) |
| Recommended Land Pattern (PC)    | 1.00mm to 1.30mm(Flow Soldering)   |
| necommended Edita i determ (i o) | 1.10mm to 1.60mm(Reflow Soldering) |

| Electrical Characteristics   |            |  |
|------------------------------|------------|--|
| Capacitance                  | 470nF ±10% |  |
| Rated Voltage                | 50VDC      |  |
| Temperature Characteristic   | X7R(±15%)  |  |
| Dissipation Factor (Max.)    | 3%         |  |
| Insulation Resistance (Min.) | 1063ΜΩ     |  |

|                       | Other                                 |  |
|-----------------------|---------------------------------------|--|
| Operating Temp. Range | -55 to 125°C                          |  |
| Coldaring Mathad      | Wave (Flow)                           |  |
| Soldering Method      | Reflow                                |  |
| AEC-Q200              | NO                                    |  |
| Packing               | Embossed (Plastic)Taping [180mm Reel] |  |
| Package Quantity      | 2000pcs                               |  |

<sup>!</sup> Images are for reference only and show exemplary products.

<sup>!</sup> This PDF document was created based on the data listed on the TDK Corporation website.

 $<sup>! \ \</sup>mbox{All specifications}$  are subject to change without notice.

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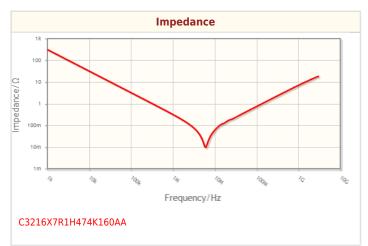


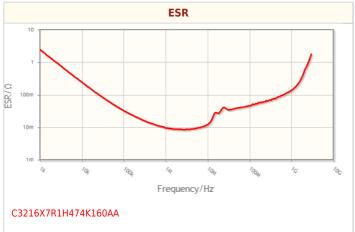


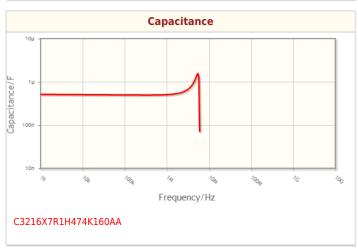


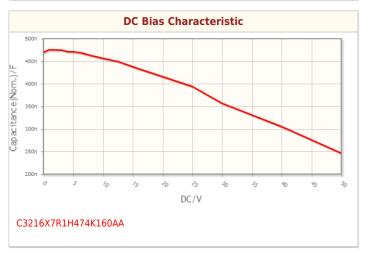


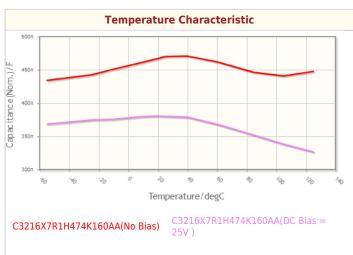
### Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

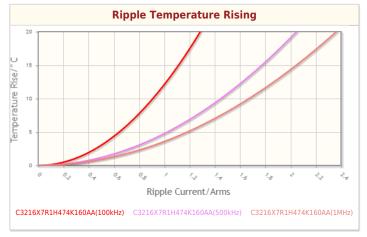












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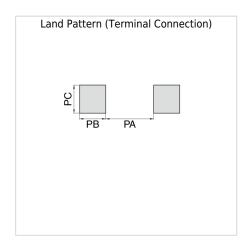








## **Associated Images**



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